

#5/17/01  
D. Rabin  
12-19-01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: To Be Assigned

Examiner: To Be Assigned



In re PATENT APPLICATION of

Applicant(s) : Takaaki SASAKI

Appln. No. : To Be Assigned

Filed : August 31, 2001

For : SEMICONDUCTOR PACKAGE FOR  
THREE-DIMENSIONAL MOUNTING,  
FABRICATION METHOD THEREOF,  
AND SEMICONDUCTOR DEVICE

Atty. Dkt. : TAI 131

**INFORMATION  
DISCLOSURE  
STATEMENT**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

This is an information disclosure statement submitted in compliance with the timing requirements of 37 C.F.R. §1.97(b)(1).

Attached is a copy of one Japanese patent publication with an English-language abstract from which the relevance of the publication may be gleaned. The publication is listed on the attached Form PTO-1449.

Since this Information Disclosure Statement is being filed with the application, no certification or fee is required, and the requirements of 37 C.F.R. §§1.97 and 1.98 are deemed to be fully met as to the document submitted. Consideration of the submitted document is respectfully requested.

Respectfully submitted,

August 31, 2001

Date

A handwritten signature in cursive script, reading "Steven M. Rabin".

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